



47A 100V N-CHANNEL POWER MOSFET

Description

The uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

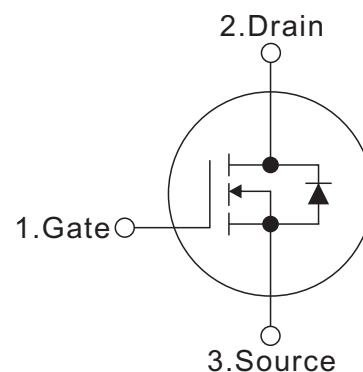
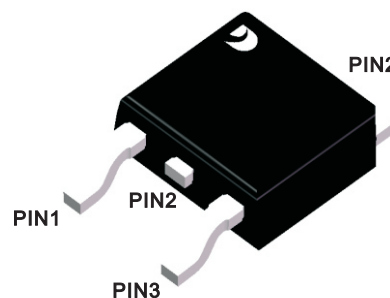
Features

- $R_{DS(ON)} < 22 \text{ m}\Omega @ V_{GS}=10\text{V}, I_D=25\text{A}$
- Fast switching capability
- Avalanche energy tested
- Improved dv/dt capability, high ruggedness

Mechanical data

- Case: TO-252W
- Approx. Weight: 0.33g (0.012oz)
- RoHS compliant
- Case Material: "Green" molding compound, UL flammability classification 94V-0, "Halogen-free".

TO-252W(Prefix :D)



Absolute Maximum Ratings (Ta=25°C, Unless Otherwise Specified)

Parameter	Symbols	Ratings	Units
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current	I_D	47 31	A
		$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	
Pulsed Drain Current (Note 2)	I_{DM}	200	A
Avalanche Energy Single Pulsed (Note 3)	E_{AS}	150	mJ
Power Dissipation ($T_c = 25^\circ\text{C}$)	P_D	115	W
Operating junction and storage temperature	T_J, T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $L = 0.5\text{mH}, V_{DD} = 50\text{V}, R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$

Thermal Resistance

Parameter	Symbols	Ratings	Units
Thermal resistance, junction – case.	R_{thJC}	1.3	$^\circ\text{C}/\text{W}$
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	130.4	$^\circ\text{C}/\text{W}$



Electrical Characteristics (ta=25°C, Unless Otherwise Specified)

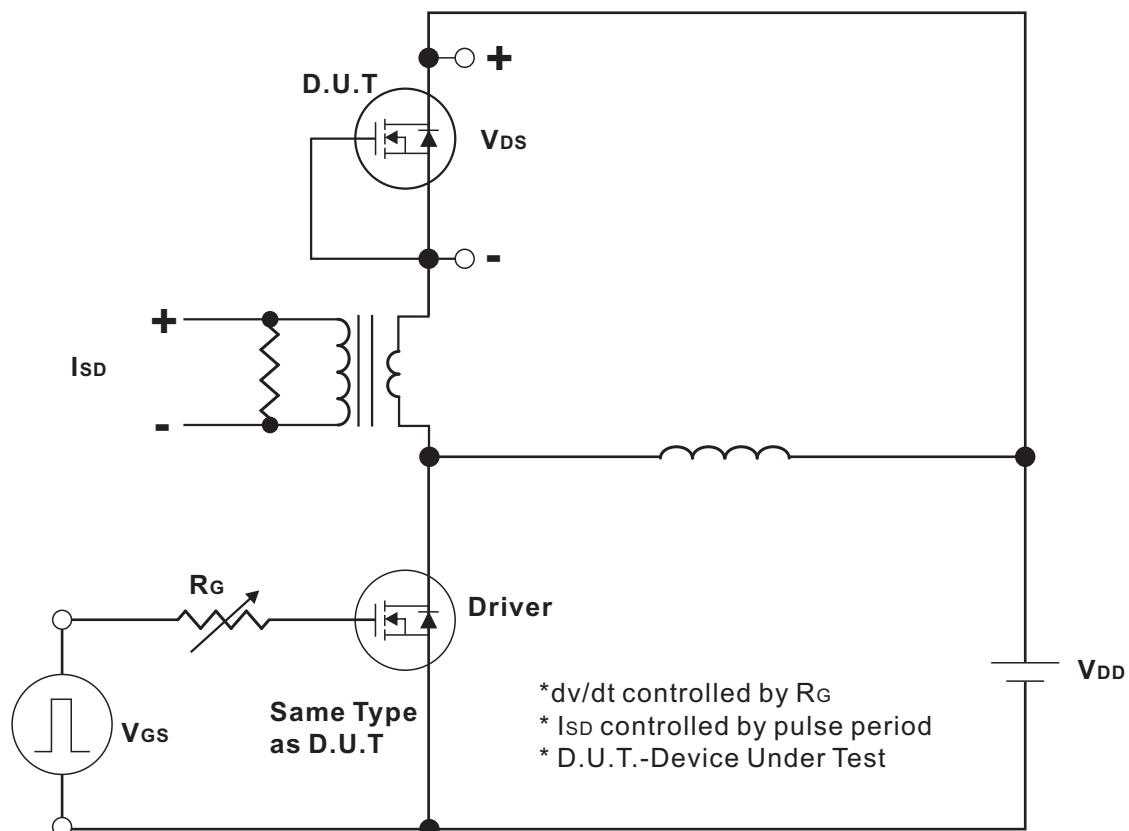
Parameter	Symbols	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1.0	μA
Gate- Source Leakage Current	Forward	I_{GSS}			100	nA
	Reverse				-100	
On Characteristics						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		2.3	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=25A$		18	22	m Ω
		$V_{GS}=4.5V, I_D=20A$		23	30	
Transconductance	g_{fs}	$V_{DS}=5V, I_D=15A$		30		S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=25V,$ $V_{GS}=0V,$ $f=1.0MHz$		1322		pF
Output Capacitance	C_{OSS}			358		pF
Reverse Transfer Capacitance	C_{RSS}			46		pF
Gate resistance	R_G			1.5		Ω
Switching Characteristics						
Total Gate Charge (Note 1)	Q_G	$V_{DS}=80V, V_{GS}=10V$ $I_D=47A$ (NOTE1,2)		17		nC
Gate-Source Charge	Q_{GS}			8.1		nC
Gate-Drain Charge	Q_{GD}			2.3		nC
Turn-On Delay Time (Note 1)	$t_{D(ON)}$	$V_{DS}=50V, I_D=47A$ $R_G=25\Omega, V_{GS}=10V$ (NOTE1,2)		24		ns
Turn-On Rise Time	t_R			13		ns
Turn-Off Delay Time	$t_{D(OFF)}$			27		ns
Turn-Off Fall Time	t_F			10		ns
Drain-Source Diode Characteristics And Maximum Ratings						
Maximum Body-Diode Continuous Current	I_S				47	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	$I_{SD}=20A, V_{GS}=0V$			1.3	V
Reverse Recovery Time (Note 1)	t_{rr}	$I_F=47A$		62		ns
Reverse Recovery Charge	Q_{rr}	$di/dt=100A/\mu s$		84		nC

Notes:

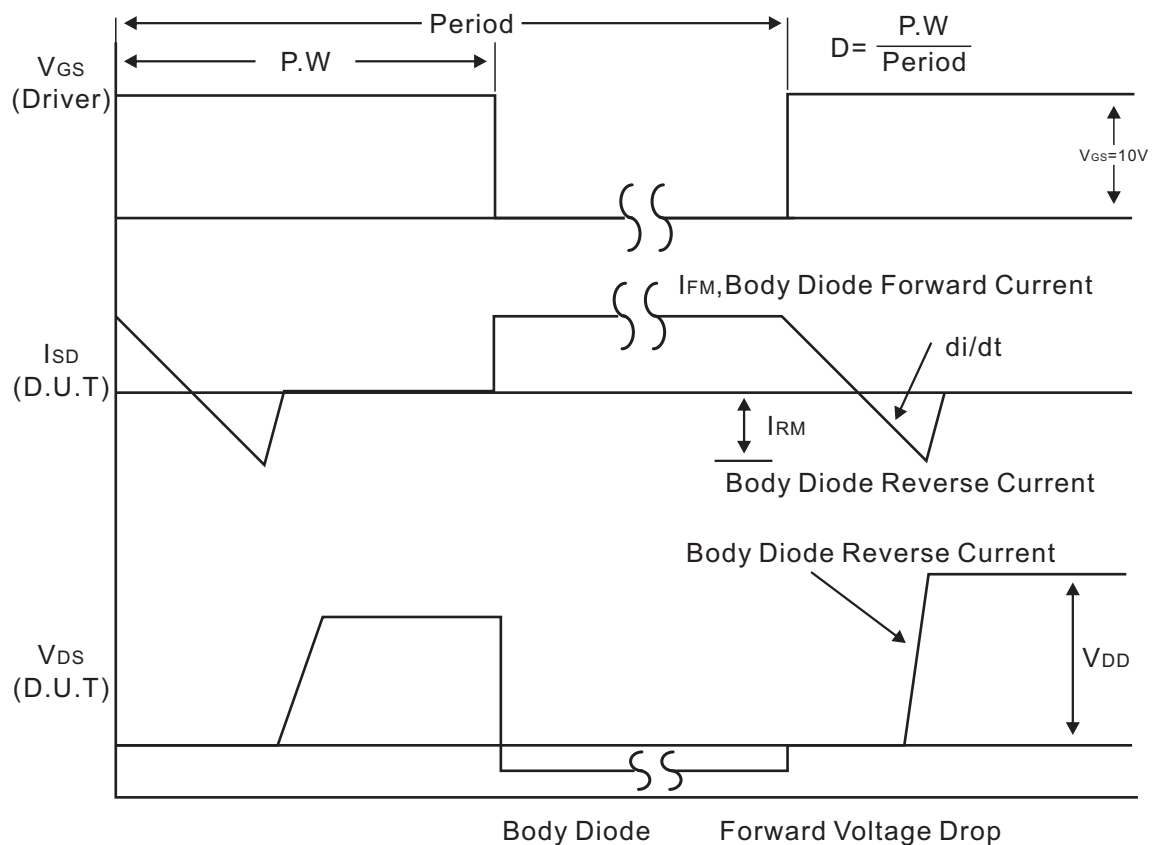
1. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
2. Essentially independent of operating temperature.



Test Circuits and waveforms



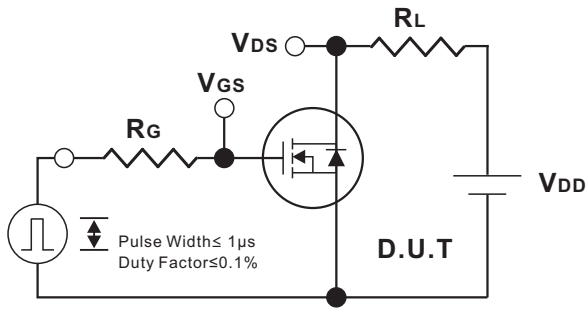
Peak Diode Recovery dv/dt Test Circuit



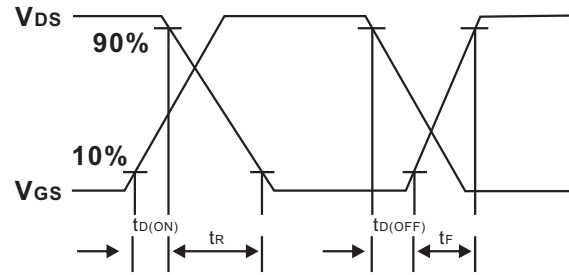
Peak Diode Recovery dv/dt Waveforms



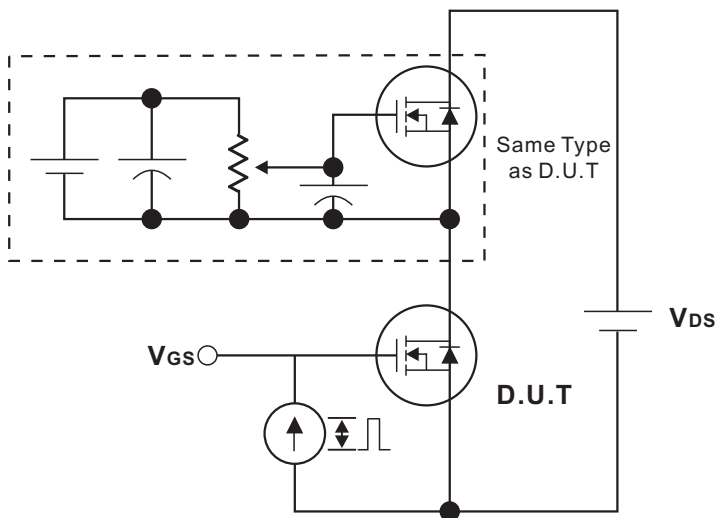
Test Circuits and waveforms



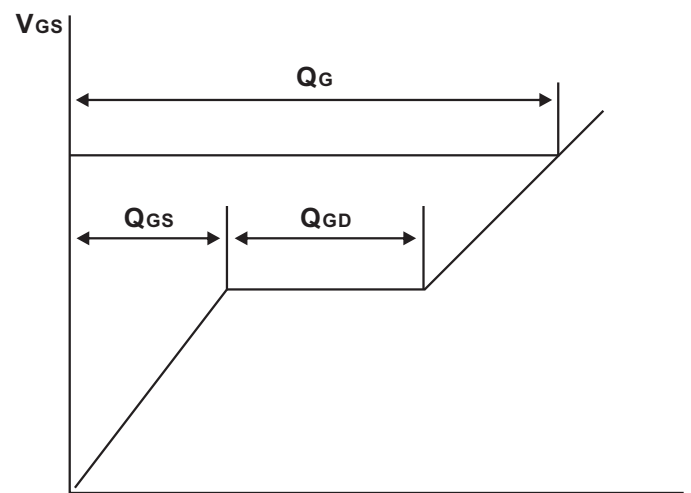
Switching Test Circuit



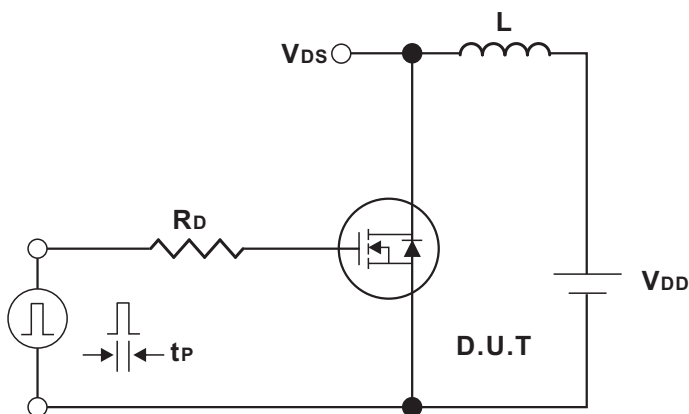
Switching Waveforms



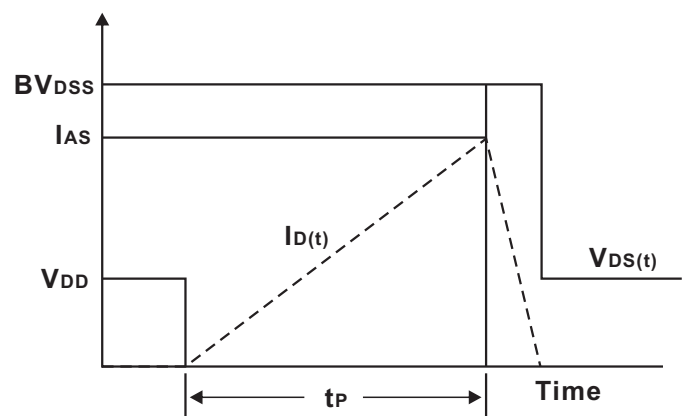
Gate Charge Test Circuit



Charge Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



Typical Characteristics

Fig.1 Typical Output Characteristics

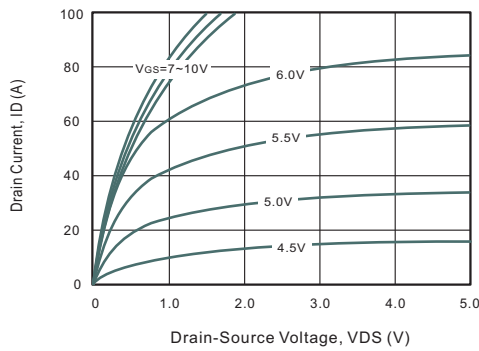


Fig.2 Power Dissipation

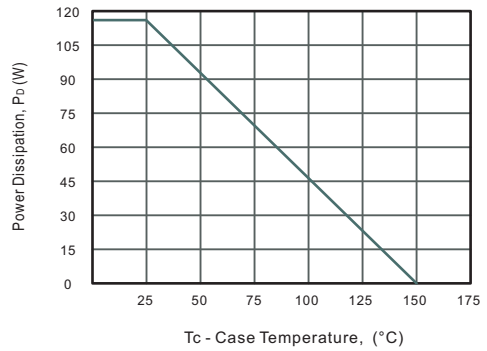


Fig.3 Drain Current Derating

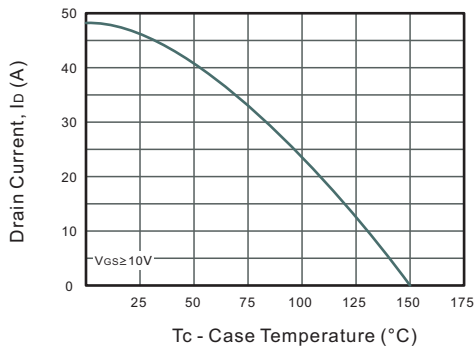


Fig.4 Drain-Source On-Resistance vs. Drain Current

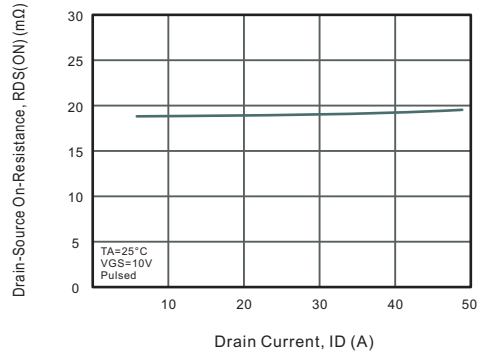


Fig.5 Gate Threshold Voltage vs. Junction Temperature

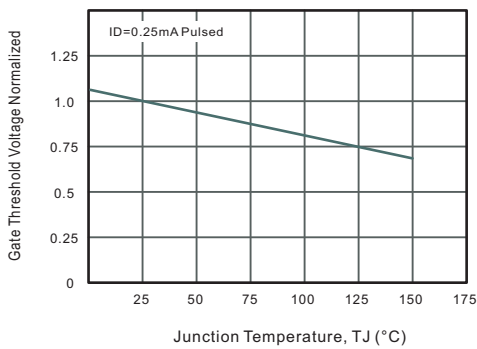


Fig.6 Body-diode Forward Characteristics

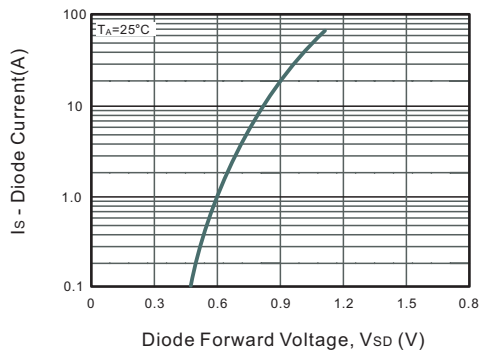


Fig.7 Drain-Source On-Resistance vs. Junction Temperature

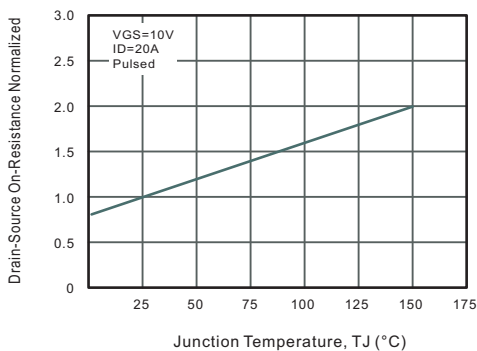
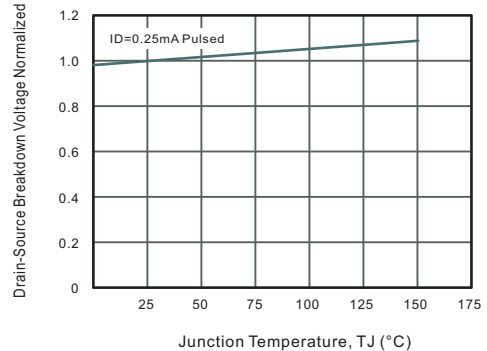
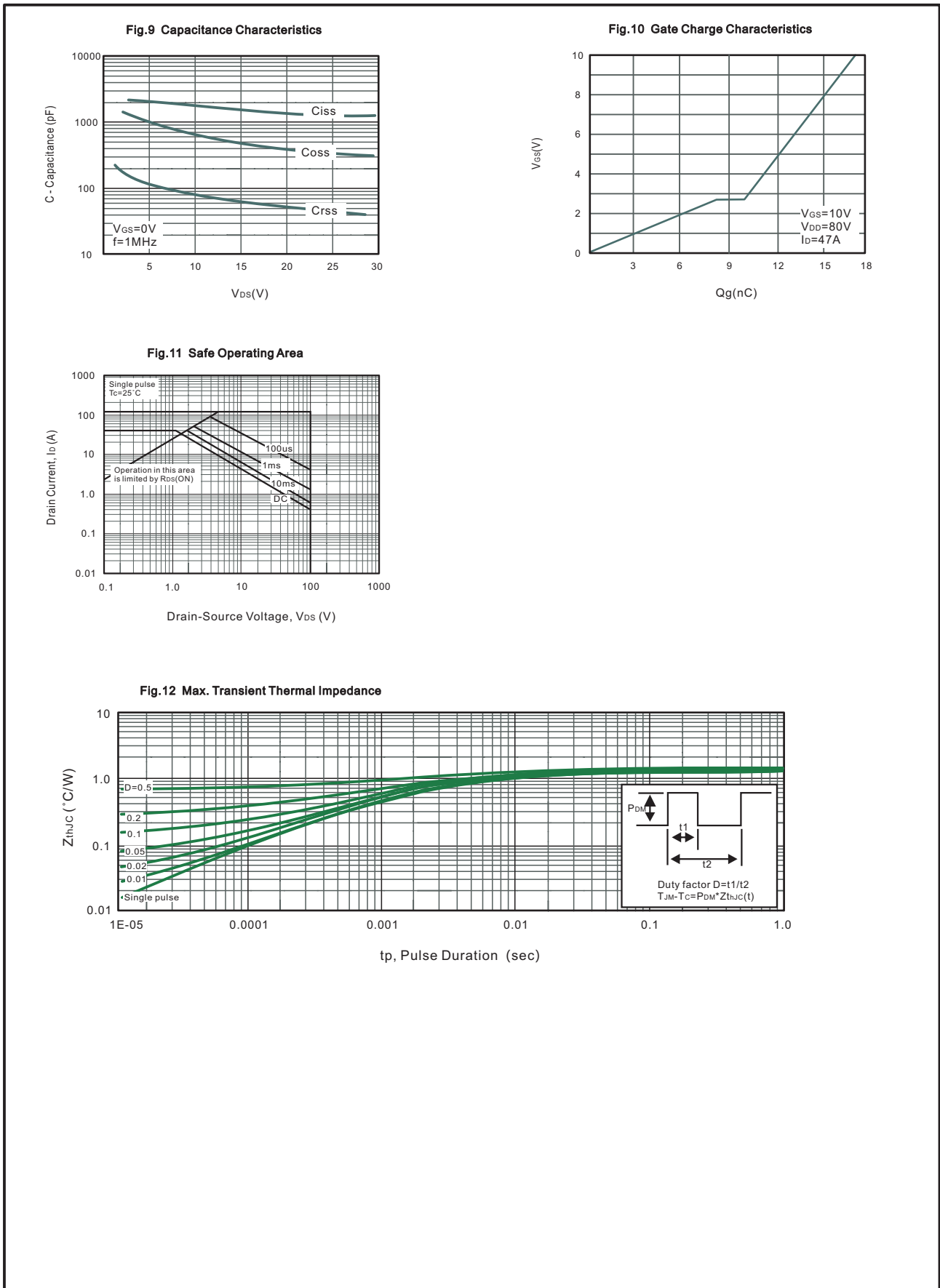


Fig.8 Breakdown Voltage vs. Junction Temperature



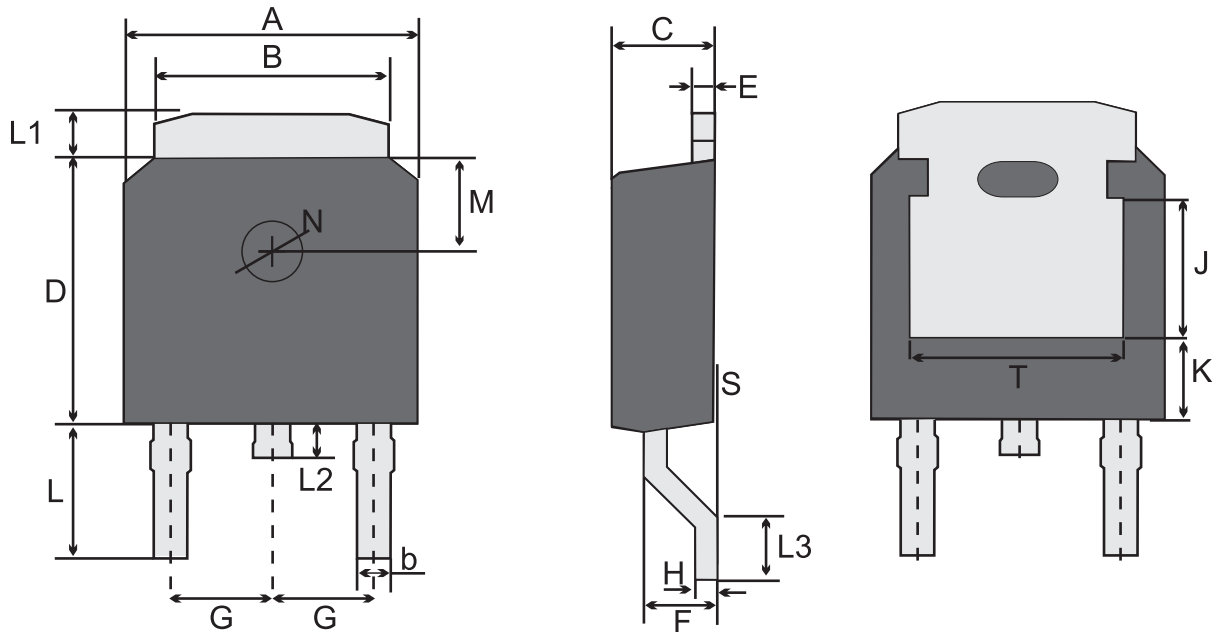


Typical Characteristics





TO-252W(D-PAK) Package Outline Dimensions



TO-252W(D-PAK)Mechanical data

UNIT		A	B	b	C	D	E	F	G	H	L	L1	L2	L3	S	M	N	J	T	K
mm	max	6.7	5.53	0.86	2.5	6.3	0.61	1.87	2.3 typ.	0.55	3.0	1.2	1.0	1.75	0.1	1.8 typ.	1.3 typ.	3.2 ref.	4.83 ref.	1.8 ref.
	typ	6.6	5.33	0.76	2.3	6.1	0.51	1.57		0.50	2.8	1.0	0.8	1.30	0.05					
	min	6.3	5.13	0.66	2.1	5.9	0.41	1.27		0.45	2.6	0.8	0.6	1.0	/					
mil	max	264	218	34	98	248	24	74	91 typ.	22	118	47	39	69	3.9	71 typ.	51 typ.	126 ref.	190 ref.	71 ref.
	typ	260	210	30	91	240	20	62		20	110	39	31	51	2.0					
	min	248	202	26	83	232	16	50		18	102	31	24	39	/					

Marking

Type number	Marking code
D18RN100XR	D18RN100XR



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